



P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)			
-60	0.012 at V _{GS} = -10 V	-60			
	$0.020 \text{ at V}_{00} = -4.5 \text{ V}$	-50			

FEATURES

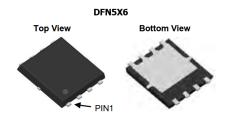
- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested
- AEC-Q101 Qualified for Automotive Applications

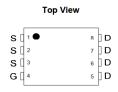


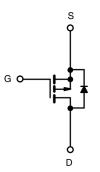
ROHS

APPLICATIONS

- Notebook
 - Load Switch







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	Limit	UNIT	
Drain-Source Voltage		V_{DS}	- 60		
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Proin Current (T = 150 °C) 8	T _A = 25 °C	1	- 60		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	l _D	- 50		
Pulsed Drain Current		I _{DM}	- 240	Α	
Continuous Source Current (Diode Conduction) ^a		I _S	- 60		
Avalanche Current	L = 0.1 mH	I _{AS}	- 62		
Single Pulse Avalanche Energy		E _{AS}	225	mJ	
Maximum Dower Discinction 3	T _A = 25 °C	D	43	W	
Maximum Power Dissipation ^a	T _A = 70 °C	P_{D}	38		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C	
Soldering Recommendations (Peak Temperature) b, c			260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	D	15	23		
Maximum Junction-to-Ambient ~	Steady State	R _{thJA}	22	35	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1	1.3		

Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. TheDFN5x6isa leadlesspackage. The endof thelead terminalisexposed copper (not plated) as a result of the singulation process in manufacturing. A solderfillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	METER SYMBOL TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static							
Gate Threshold Voltage	Threshold Voltage $V_{GS(th)}$ $V_{DS} = V_{GS}$, $I_D = -250 \mu A$		-1	-	-3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA	
Zero Gate Voltage Drain Current	1	$V_{DS} = -48 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	-1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = -48 V, V_{GS} = 0 V, T_J = 70 °C	-	-	-10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	-60	-	-	Α	
Drain Course On State Resistance 3	Б	$V_{GS} = -10 \text{ V}, I_D = -15 \text{ A}$	-	0.012	0.0145	$ \Omega$	
Drain-Source On-State Resistance a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -10 \text{ A}$	-	0.020	0.0250		
Forward Transconductance a	9 _{fs}	$V_{DS} = -15 \text{ V}, I_D = -15 \text{ A}$	-	31	-	S	
Diode Forward Voltage ^a	V _{SD}	$I_S = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$	-	-0.7	-1.2	V	
Dynamic ^b							
Total Gate Charge	Qg		-	121	190		
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -15 \text{ A}$	-	20	-	nC	
Gate-Drain Charge	Q _{gd}		-	32	-		
Gate Resistance	R_g		-	3	-	Ω	
Turn-On Delay Time	t _{d(on)}		-	20	30		
Rise Time	t _r	V_{DD} = -30 V, R_L = 30 Ω	-	20	30		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ -15 A, $V_{GEN}=$ -10 V, $R_g=6~\Omega$	-	205	310	ns	
Fall Time	t _f		-	90	135		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = -4.5 A, dl/dt = 100 A/μs	-	45	70		

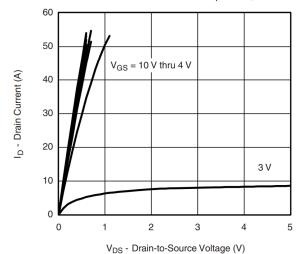
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

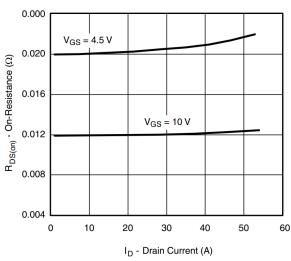
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



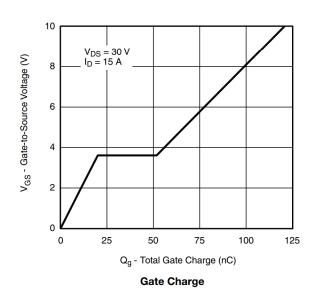
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

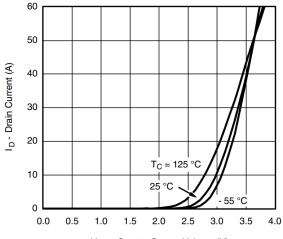


Output Characteristics



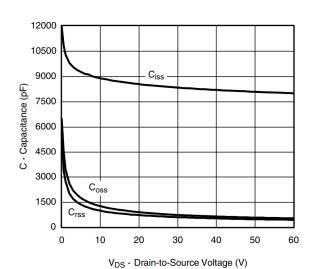
On-Resistance vs. Drain Current



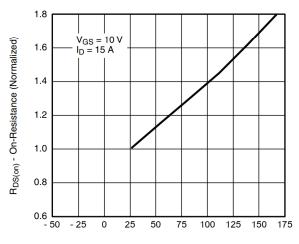


V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



Capacitance

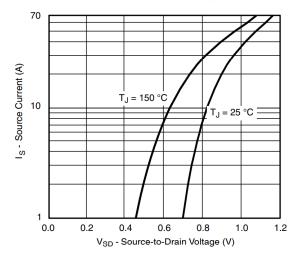


T_J - Junction Temperature (°C)

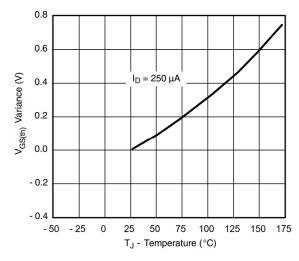
On-Resistance vs. Junction Temperature



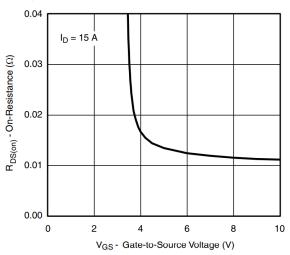
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



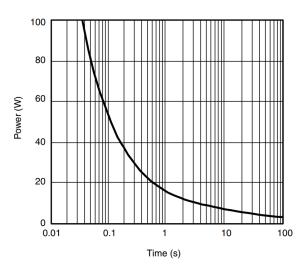
Source-Drain Diode Forward Voltage



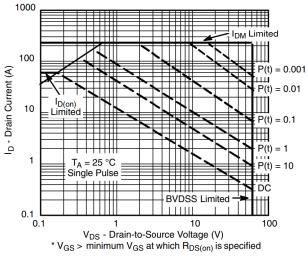
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



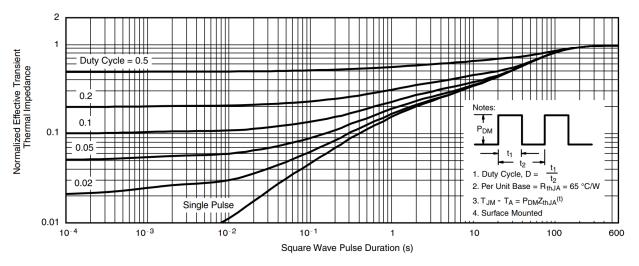
Single Pulse Power, Junction-to-Ambient



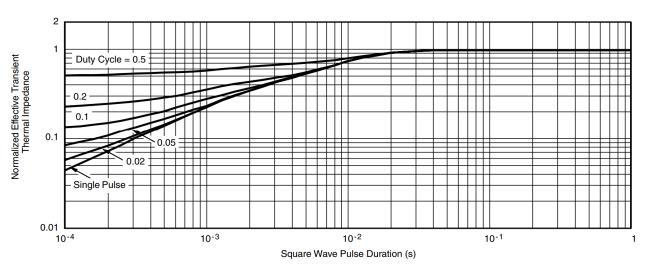
Safe Operating Area



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



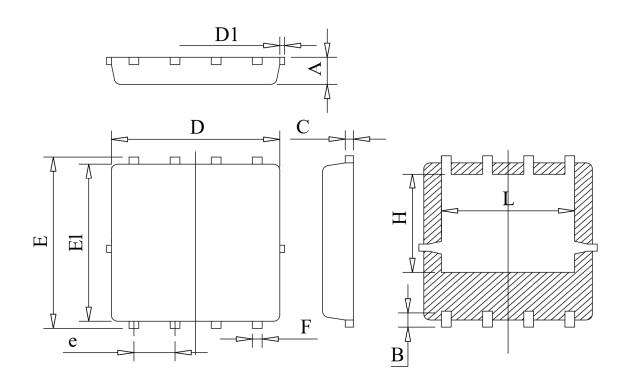
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case



DFN5X6-8L PACKAGE OUTLINE



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Unit: mm

Symbol	Min	Тур	Max
A	0.78	0.95	1.12
В	0.45	0.58	0.78
С	0.18	0.254	0.36
D	4.70	5.20	5.45
D1			0.18
Е	5.85	6.05	6.25
E1	5.38	5.55	5.98
e	1.15	1.27	1.40
F	0.18	0.30	0.52
Н	3.25	3.47	3.70
L	3.75	4.00	4.25





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